

Title (en)  
FAST CURING EPOXY SYSTEMS

Title (de)  
SCHNELL HÄRTENDE EPOXYSYSTEME

Title (fr)  
SYSTÈMES ÉPOXYDIQUES À DURCISSEMENT RAPIDE

Publication  
**EP 3569631 B1 20220713 (DE)**

Application  
**EP 19174659 A 20190515**

Priority  
EP 18172949 A 20180517

Abstract (en)  
[origin: JP2019199609A] To provide an epoxy type which more quickly responds than a conventionally known compound under the same condition, and to provide an epoxy compound which is more quickly initially cured or cured than a conventional compound at a temperature clearly below room temperature.SOLUTION: There are provided a composition which contains a) at least one epoxy resin, b) at least one cyclic amine of Formula (I), and c) at least one Broensted strong acid salt having counter ions selected from metal ions, metal-containing ions, phosphonium ions and unsubstituted ammonium ions, in which a ratio of the epoxy groups of the epoxy resin to the total of the total NH groups of the total amine is 0.5:1 to 1.5:1; and a method for producing the same and a use of the same.SELECTED DRAWING: None

IPC 8 full level  
**C08G 59/50** (2006.01)

CPC (source: CN EP KR US)  
**C08G 59/22** (2013.01 - KR); **C08G 59/245** (2013.01 - US); **C08G 59/28** (2013.01 - US); **C08G 59/5026** (2013.01 - EP); **C08G 59/5046** (2013.01 - EP US); **C08G 59/506** (2013.01 - CN EP); **C08G 59/5073** (2013.01 - CN); **C08G 59/5086** (2013.01 - KR); **C08G 59/58** (2013.01 - KR); **C08G 59/68** (2013.01 - CN KR); **C08G 59/686** (2013.01 - CN); **C08L 63/00** (2013.01 - KR); **C09D 163/00** (2013.01 - US); **C09J 163/00** (2013.01 - US); **C08G 59/5026** (2013.01 - US); **C08G 59/5033** (2013.01 - US); **C08K 5/19** (2013.01 - US); **C08K 5/50** (2013.01 - US)

Cited by  
EP3981817A1; US11453744B2

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
**EP 3569631 A1 20191120; EP 3569631 B1 20220713**; CN 110498903 A 20191126; JP 2019199609 A 20191121; JP 7411339 B2 20240111; KR 20190132247 A 20191127; US 11359048 B2 20220614; US 2019352451 A1 20191121

DOCDB simple family (application)  
**EP 19174659 A 20190515**; CN 201910406039 A 20190516; JP 2019093868 A 20190517; KR 20190057272 A 20190516; US 201916408725 A 20190510